

## AMENDMENTS TO THE CLAIMS

Claims 1-16 (cancelled)

1 Claim 17 (original): A semiconductor device including a plurality of chips, the chips having  
2 front surfaces and back surfaces, the device comprising:  
3 a support attached to the chips on the back surfaces thereof;  
4 a first layer disposed on the front surfaces of the chips and having a plurality of vias  
5 formed therein and conducting pads in registration with the vias;  
6 a plurality of studs corresponding to the vias and disposed therein; and  
7 a second layer attached to the first layer on a surface of the first layer opposite the front  
8 surfaces of the chips, the second layer being aligned to the first layer by the studs in the vias,  
9 the second layer including electrical wiring connecting to the chips through the studs and the  
10 conducting pads,  
11 wherein said plurality of chips includes chips with active devices and a chip without  
12 active devices.

1 Claim 18 (original): A semiconductor device according to claim 17, further comprising an  
2 attachment layer between the support and the chips, wherein the attachment layer has a  
3 plurality of support connection vias formed therein, support connection pads in registration  
4 with the support connection vias, and a plurality of support connection studs disposed in the  
5 support connection vias and connected to the support connection pads.

1 Claim 19 (original): A semiconductor device according to claim 17, wherein the chip without  
2 active devices has passive components fabricated thereon.

1 Claim 20 (original): A semiconductor device according to claim 17, wherein the chip without  
2 active devices has a size according to a placement pattern of the chips with active devices.